



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-11-28
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SMP30-240	8HST*CWB240K	A	64BA	2017-11-28
Amount	UoM	Unit type	ST ECOPACK Grade	
70.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.14-2.76-1.94	2	J bend	
Comment	SMA			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	Die back side metal	86
Lead	0.88	Soft solder	12571

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	8H5T*CW8240K		70.0000								
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)					
Die	Other inorganic materials	0.810	mg	supplier	die	Silicon (Si)	7440-21-3		0.792	mg	977778	11314					
				supplier	metallization	Aluminium (Al)	7429-90-5		0.003	mg	3704	43					
				supplier	Passivation	Silicon Oxide	7631-86-9		0.004	mg	4938	57					
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.004	mg	4938	57					
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1235	14					
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.006	mg	7407	86					
Leadframe	Copper & its alloys	29.806	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.767	mg	988692	425243					
				supplier	alloy	Iron (Fe)	7439-89-6		0.030	mg	1007	429					
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.009	mg	302	129					
				supplier	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high met	0.880	mg	919540	12571				
Soft solder	Solder	0.957	mg	supplier	solder	Silver (Ag)	7440-22-4		0.024	mg	25078	343					
				supplier	solder	Tin (Sn)	7440-31-5		0.048	mg	50157	686					
				supplier	solder	Flux residue	Proprietary		0.005	mg	5225	71					
				supplier	Encapsulation	Other Organic Materials	26.205	mg	supplier	mold compound	Amorphous Silica	7631-86-9		19.156	mg	731005	273656
				supplier	mold compound	Epoxy Cresol Novolak	29680-82-2		4.979	mg	190002	71129					
supplier	mold compound	Phenol resin	9003-35-4		0.786	mg	29994	11229									
supplier	mold compound	Bisphenol A-bisphenol A diglycidyle ether poly	25036-25-3		0.786	mg	29994	11229									
supplier	mold compound	Carbon black	1333-86-4		0.236	mg	9006	3371									
supplier	mold compound	Triphenylphosphine	603-35-0		0.183	mg	6983	2614									
supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		0.079	mg	3015	1129									
Connections coating	Solder	0.741	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.741	mg	1000000	10586					
Clip	Copper & its alloys	11.481	mg	supplier	alloy	Copper (Cu)	7440-50-8		11.481	mg	1000000	164014					